

Partial | **EAST Search History**

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|---|------------------|---------|------------------|
| L1 | 2940 | 257/778.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/10/15 20:54 |
| L2 | 2342 | 257/737.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/10/15 20:55 |
| L3 | 1 | ((conductive adj bump) and (semiconductor adj chip) and (surface with (bonding adj pad)) and (first adj metal) and (conductive adj paste) and (second adj metal) and (base adj portion) and (peripheral adj portion)). clm. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/10/15 20:57 |
| S1 | 2 | ("6159837").PN. | USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/07/25 15:52 |